What is Claimed is:

1. A multilayer electronic component having a multilayered product laminating a plurality of dielectric sheets as one piece,

a plurality of grounded electrodes provided among said dielectric sheets being different inside said multilayered product, and

inductor electrodes provided on said dielectric sheet surfaces not having said plurality of grounded electrodes inside said multilayered product,

wherein all or part of said inductor electrodes are placed so as not to be sandwiched by said plurality of grounded electrodes.

2. The multilayer electronic component according to claim 1, wherein the part of said inductor electrodes not sandwiched by said plurality of grounded electrodes is one portion of one inductor electrode.

3. The multilayer electronic component according to claim 1, wherein the part of said inductor electrodes not sandwiched by said plurality of grounded electrodes are one piece or a plurality of pieces of a plurality of the inductor electrodes.

4. The multilayer electronic component according to claim 1, wherein all or part of said inductor electrodes not sandwiched by said plurality of grounded electrodes are placed

on the dielectric sheets not sandwiched by said plurality of grounded electrodes.

5. The multilayer electronic component according to claim 1, wherein all or part of said inductor electrodes not sandwiched by said plurality of grounded electrodes are placed on the dielectric sheets sandwiched by said plurality of grounded electrodes.

6. The multilayer electronic component according to claim 1 or 2, wherein part of said inductor electrodes not sandwiched by said plurality of grounded electrodes are formed by having slots formed on said grounded electrodes overlap said inductor electrodes.

7. The multilayer electronic component according to claim 1 or 3, wherein all of said inductor electrodes not sandwiched by said plurality of grounded electrodes are formed by having slots having substantially the same shape as said inductor electrodes formed on said grounded electrodes overlap said inductor electrodes.

8. The multilayer electronic component according to claim 2 or 3, wherein part and other remaining portions of said inductor electrodes not sandwiched by said plurality of grounded electrodes are placed on said dielectric sheets that are the same.

9. A multilayer electronic component having a multilayered product laminating a plurality of dielectric sheets as one piece,

a plurality of grounded electrodes provided among said dielectric sheets being different inside said multilayered product, and

a plurality of inductor electrodes provided on said dielectric sheet surfaces not having said plurality of grounded electrodes inside said multilayered product, and

internal grounded electrodes provided among said plurality of inductor electrodes.

10. The multilayer electronic component according to claim 9, wherein said internal grounded electrodes are connected to said plurality of grounded electrodes via holes.

11. The multilayer electronic component according to claim 9, wherein all or part of said plurality of inductor electrodes are placed on said dielectric sheets that are the same.

12. The multilayer electronic component according to claim 6, wherein a direction in which said slots draw is orthogonal to the direction in which said inductor electrodes draw.

13. The multilayer electronic component according to claim 12, wherein said inductor electrodes have a spiral shape.

14. The multilayer electronic component according to claim 12, wherein said inductor electrodes have a meander shape.

15. The multilayer electronic component according to claim 1, wherein an inductor comprised of all or part of said inductor electrodes placed not to be sandwiched by said plurality of grounded electrodes is used as a choke coil.

16. The multilayer electronic component according to claim 3,

wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a low-pass filter, and

the inductor comprised of the inductor electrodes other than said part thereof is used in a high-pass filter.

17. The multilayer electronic component according to claim 3,

wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a band pass filter, and

the inductor comprised of the inductor electrodes other than said part thereof is used in a high-pass filter.

18. The multilayer electronic component according to claim 3,

wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a low-pass filter, and

the inductor comprised of the inductor electrodes other than said part thereof is used in a band pass filter.

19. The multilayer electronic component according to claim 3, wherein first inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a band pass filter, and the inductor comprised of the inductor electrodes other than said part thereof is used in a band pass filter of a frequency band higher than the band pass filter using the inductor formed by said first inductor electrodes.

20. The multilayer electronic component according to claim 3, wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a GSM circuit, and the inductor comprised of the inductor electrodes other than said part thereof is used in a DCS circuit.

21. The multilayer electronic component according to claim 3, wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in an AMPS circuit, and the inductor comprised of the inductor electrodes other than said part thereof is used in a CDMA2000 circuit.

22. The multilayer electronic component according to claim 3, wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a PDC circuit, and the inductor comprised

of the inductor electrodes other than said part thereof is used in a W-CDMA circuit.

23. The multilayer electronic component according to claim 3,

wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a GSM circuit, and

the inductor comprised of the inductor electrodes other than said part thereof is used in a W-CDMA circuit.

24. The multilayer electronic component according to claim 3,

wherein an inductor comprised of part of said inductor electrodes not to be sandwiched by said plurality of grounded electrodes is used in a DCS circuit, and

the inductor comprised of the inductor electrodes other than said part thereof is used in a W-CDMA circuit.

25. A communication apparatus having:

reception means of receiving a signal from an antenna, having at least a low noise amplifier, a filter and a mixer;

transmission means of transmitting the signal from said antenna, having at least a mixer, a filter and a power amplifier;

an antenna switch for switching a connection between said antenna and said reception means or said transmission means, whereas:

the multilayer electronic component according to any of claims 1 to 24 is used in all or part of the filter of said transmission means, the filter of said reception means, and said antenna switch.